

10-17-2003



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1. Name of conveying party(ies):

Bin Yang
Sanford Chu
Wensheng Qian
Tan Li Jia

10-2-03

Additional names(s) of conveying party(ies)

☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ OtherExecution Date: aug 18,2003 Sept 4,2003

2. Name and address of receiving party(ies):

Name: Chartered Semiconductor Manufacturing LTDAddress: 60 Woodlands Industrial Park D

Street 2

City: SingaporeState/Prov.: SGCountry: SingaporeZIP: 7384066

Additional name(s) & address(es)

☐ Yes ☒ No

4. Application number(s) or patent numbers(s):

If this document is being filed together with a new application, the execution date of the application is: aug 18,03 Sep 4,2003

Patent Application No.

Filing date

B. Patent No.(s)

10/08/2003 FFAMAEIA 00000070 10677830

02 FC:8021

40.00 OP

Additional numbers

☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: William J StoffelRegistration No. 39,390 Customer no. 30402Address: 1735 Market St - Ste APMB 455City: PhiladelphiaState/Prov.: PACountry: USAZIP: 19103

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41):.....\$ 40.00☒ Enclosed - Any excess or insufficiency should be credited or debited to deposit account☐ Authorized to be charged to deposit account

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*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*William J. Stoffel

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Signature10/1/03

Date

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Assignment of Rights, Title and Interest in Invention
(Multiple inventors; single assignee)

Docket No.
CS02-090

This is an Assignment of the following rights, title and interest: (check all that apply):

- ☒ *United States of America rights, title and interest in the invention*
☒ *Foreign rights, title and interest in the invention*
☒ *United States Patent Application Serial No.* _____ *application attached*

Date of Execution: _____

Date of Filing: _____

- ☐ *United States Provisional Patent Application Serial No.* _____
☐ *United States Patent No(s).* _____
☐ *International (PCT) Patent Application Serial No.* _____
☐ *Other (specify)* _____

Title of the Invention

: Method for forming a MIM capacitor

Inventors (assignors)

Name	Address	St
Bin Yang	BLK148, #10-285, Gangsa Rd, Singapore	670148
Sanford Chu	9 Beechwood Grove, Singapore	727927 SG
Wensheng Qian Wensheng Qian	Blk 130, YISHUN St. 11, #05-259, Singapore	760130
Tan Li Jia	Blk148, #10-285, Gangsa Rd, Singapore	670148 SG
Chang Chuan Hu	Blk 637, Yishun St. 61 #10-116, Singapore	760637 SG

Assignee

Name	Address
Chartered Semiconductor Manufacturing LTD	60 Woodlands Industrial Park D Street 2 Singapore Singapore 738406 SG

**Assignment of Rights, Title and Interest in Invention
(Multiple inventors; single assignee)**

Docket No.
CS02-090

Whereas, we, the above-identified Inventors, have invented certain new and useful improvements in the Invention identified above and described in the above-identified patent application(s) and/or patent(s) (hereinafter referred to as "Invention");

And, whereas we desire to assign our above-identified rights, title and interest in the Invention to the above-identified Assignee;

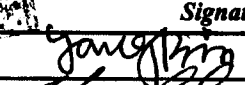
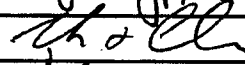
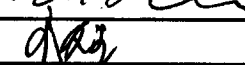
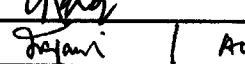
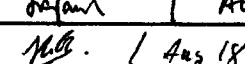
Now, this indenture witnesseth, that for good and valuable consideration, the receipt whereof is hereby acknowledged;

We hereby assign, sell and transfer our above-identified rights, title and interest in said Invention, said application(s) as identified above, including any divisions, continuations, and continuations-in-part thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted or have granted for said Invention, and in and to any and all reissues and reexaminations thereof, and in and to any and all priority rights, Convention rights, and other benefits accruing or to accrue to us with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, unto said Assignee;

And we hereby authorize and request the Commissioner of Patents and Trademarks to issue any United States Letters Patent which may issue for said Invention to said Assignee, as assignee of the whole right, title and interest thereto;

And we further agree to sign and execute all necessary and lawful future documents, including applications for foreign patents, for filing divisions, continuations and continuations-in-part of said application for patent, and/or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid Invention, as the Assignee or its Designee(s) may from time to time require and prepare at its own expense.

Inventors' Signatures (if Notarization is desired, do not sign here and proceed to next page)

Name	Signature/Date
Bin Yang	 18/08/03
Sanford Chu	 18/8/03
Wensheng Qian Wensheng Qian	
Tan Li Jia	 Aug. 18, 2003
Chang Chuan Hu	 18/8/2003